

N-Channel 30-V (D-S) MOSFET

Description

These miniature surface mount MOSFETs utilize High Cell Density process. Low rDS(on) assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are lower voltage application, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones

RoHS

Features

- · Low rDS(on) trench technology
- · Fast switching speed
- · Low thermal impedance
- RoHS compliant package

Applications:

- · Power Routing
- · Li Ion Battery Packs
- · Level Shifting and Driver Circuits

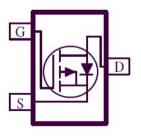
Package type: SC70-3

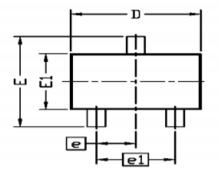
Packing & Order Information

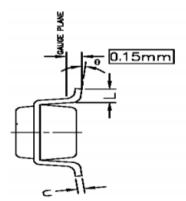
3.000/Reel

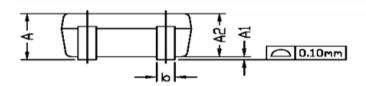


Graphic symbol









SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES			
SIMBULS	MIN	NOM	MAX	MIN	NOM	MAX	
Α		I	1.10			0.043	
A1	0.00		0.10	0.00		0.004	
A2	0.7	0.9	1.00	0.028	0.035	0.039	
ь	0.15		0.30	0.006		0.012	
c	0.08		0.22	0.003		0.009	
D	1.85	2.10	2,15	0.073	0.083	0.085	
E	1.80	2.30	2.40	0.071	0.091	0.094	
е	0.65 BSC			0.026 BSC			
el	1.30 BSC			0.051 BSC			
E1	1.1	1.30	1.4	0.043	0.051	0.055	
L	0.26	0.36	0.46	0.010	0.014	0.018	
θ	0°	4°	8°	0°	4°	8°	



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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T _A =25°C unless otherwise specified)					
Symbol	Parameter Value		Unit		
V_{DS}	Drain-Source Voltage	30	V		
V_{GS}	Gate-Source Voltage	±20	V		
τ_	Continuous Drain Current ^a (T _A =25°C)	2.0	A		
I_D	Continuous Drain Currenta (T _A =70°C)	1.6	A		
I_{DM}	Pulsed Drain Current ^b	10	A		
Is	Continuous Source Current (Diode Conduction) ^a	0.45	A		
P_D	Power Dissipation ^a (T _A =25°C)	0.34	W		
	Power Dissipation ^a (T _A =70°C)	0.22	W		
T _J /T _{STG}	Operating Junction and Storage Temperature	-55 to +150	°C		

Thermal Resistance Ratings						
Symbol	Parameter	Maximum	Units			
R_{THJA}	Maximum Junction-to-Ambient C/W ^a (t <= 10 sec)	375	°C/W			
	Maximum Junction-to-Ambient C/W ^a (Steady-State)	430	C/ vv			

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Static						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
V_{GS}	Gate Threshold Voltage	$V_{DS}=V_{GS},I_D\!=\!\text{-}250\mu\text{A}$	1			V
IGSS	Gate-Body Leakage	$V_{DS} = 0 V$, $V_{GS} = \pm 20 V$			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \ V$, $V_{GS} = 0 \ V$ $V_{DS} = 24 \ V$, $V_{GS} = 0 \ V$, $T_{J} = 55 \ ^{\circ}C$			1 10	uA
$I_{D(on)}$	On-State Drain Current ^A	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	3			A
R _{DS(on)}	Drain-Source On-Resistance ^A	$V_{GS} = 10 \text{ V}, I_D = 1.6 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 1.3 \text{ A}$			58 82	mΩ
g fs	Forward Tranconductance ^A	$V_{DS} = 15 \text{ V}, I_{D} = 1.6 \text{ A}$		4		S
V _{SD}	Diode Forward Voltage	$I_S=0.25\ V\ ,\ V_{GS}=0\ V$		0.74		V

Dyna mic ^b							
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 15 \text{ V}, R_L = 9.4 \Omega,$ $V_{GEN} = 10 \text{ V}, R_{GEN} = 6 \Omega$ $I_D = 1.6 \text{ A}$		4		ns	
$t_{\rm r}$	Rise Time			7		ns	
$t_{ m d(off)}$	Turn-Off Delay Time			19		ns	
tf	Fall Time			5		ns	



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Dynamic ^b						
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Units
$Q_{\rm g}$	Total Gate Charge	$V_{DS} = 15 \text{ V}, I_D = 1.6 \text{ A}$ $V_{GS} = 4.5 \text{ V}$		5.9		nC
Q_{gs}	Gate-Source Charge			2.1		nC
Q_{gd}	Gate-Drain Charge	VGS - 4.3 V		2.1		nC
C_{ISS}	Input Capacitance	$\begin{split} V_{GS} &= 0 \ V \ , \\ V_{DS} &= 15 \ V \ , \ f = 1 MHz \end{split}$		513		pF
Coss	Output Capacitance			69		pF
Crss	Reverse Transfer Capacitance			54		pF

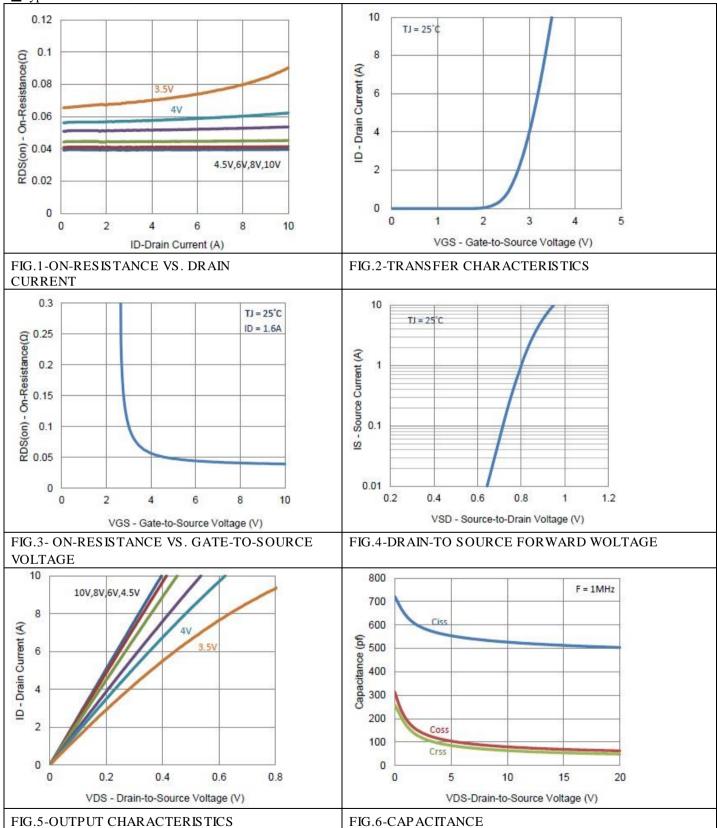
Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.



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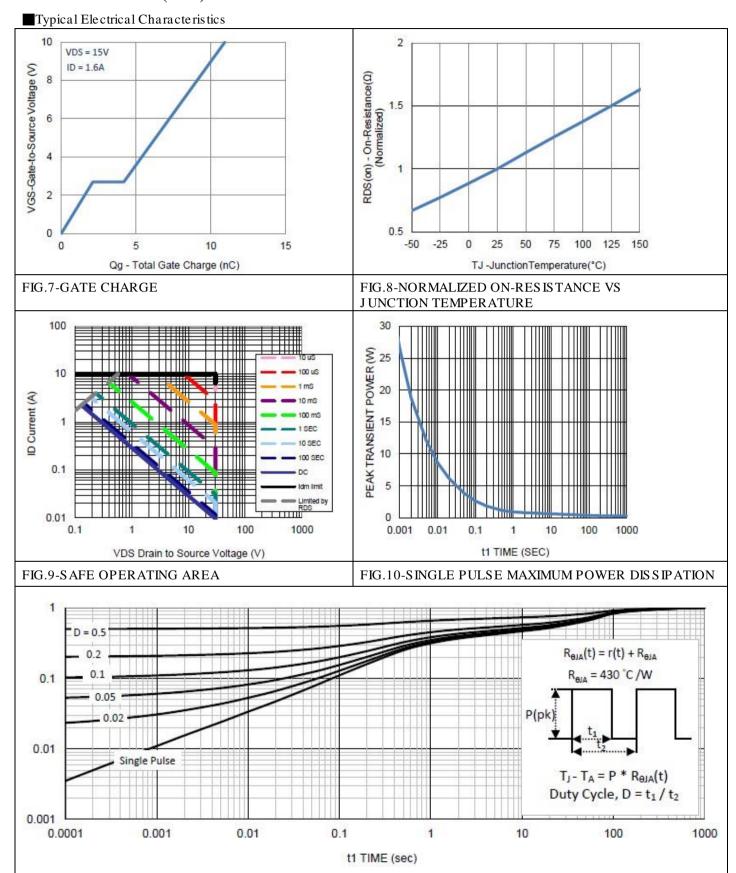


FIG.11-NORMALIZED THERMAL TRANSIENT JUNCTION TO AMBIENT



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